

MODEL: HSS26-B20-P38 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 or TO-218 package
- solder pin
- aluminum alloy



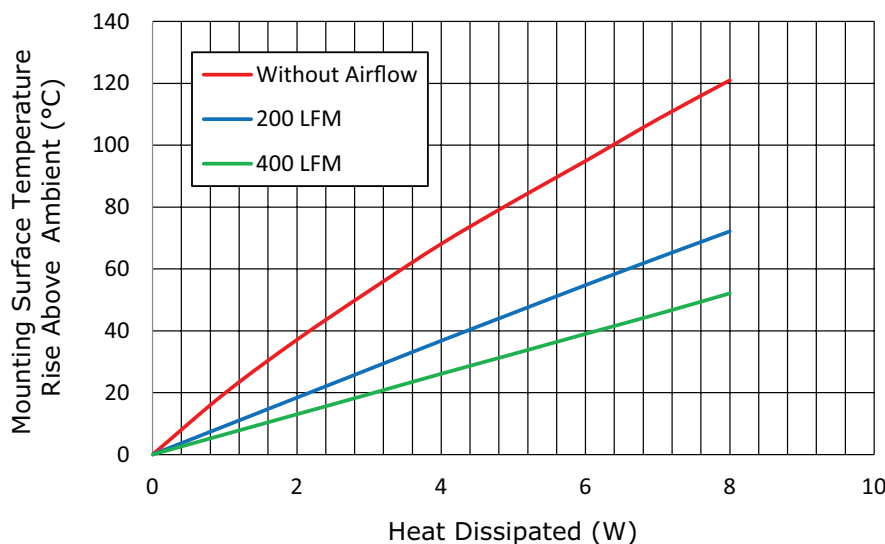
MODEL

HSS26-B20-P38	thermal resistance ¹			power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	16.66	19.8	9.2	4.50

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	19.8	9.2	6.5
2	37.1	18.4	13.0
3	52.9	27.6	19.5
4	68.1	36.8	26.1
5	81.8	45.8	32.5
6	94.9	54.8	39.0
7	108.4	63.6	45.4
8	121.0	72.2	52.1

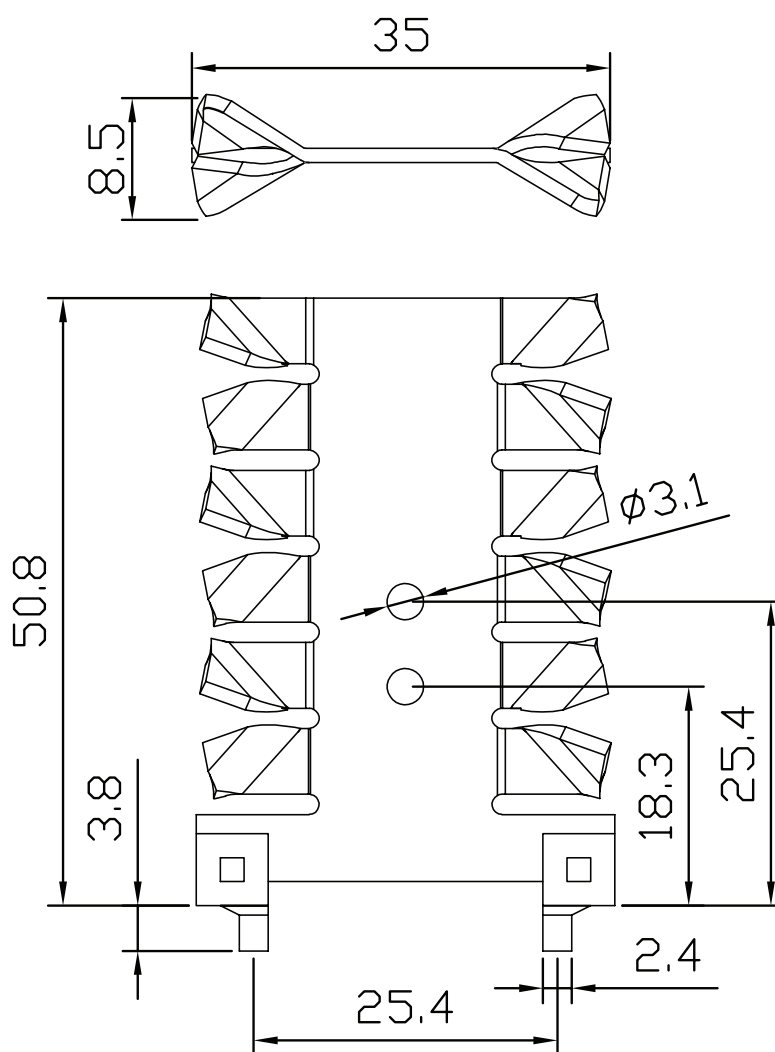


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.5 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	6.2 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/20/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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